

## STN4828-VB Datasheet

## Dual N-Channel 60 V (D-S) 175 °C MOSFET

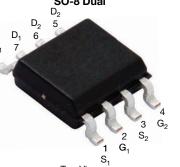
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	60			
$R_{DS(on)} (\Omega)$ at $V_{GS} = 10 V$	0.028			
$R_{DS(on)} (\Omega)$ at $V_{GS} = 4.5 V$	0.030			
I <sub>D</sub> (A) per leg	7			
Configuration	Dual			

#### $\underset{\mathsf{D}_2}{\textbf{SO-8 Dual}}$ $\mathsf{D}_2$ 5 $D_1$ 6 $D_1$ 8 $G_2$ $S_2$ G₁ $S_1$ Top View

#### **FEATURES**

- TrenchFET<sup>®</sup> power MOSFET
- 100 %  $R_g$  and UIS tested





D G1 G2 C S<sub>1</sub>  $S_2$ 

COMPLIANT HALOGEN

N-Channel MOSFET N-Channel	nel MOSFET
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<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V <sub>DS</sub>	60	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current	T <sub>C</sub> = 25 °C	1	7		
	T <sub>C</sub> = 125 °C	- I <sub>D</sub>	4		
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	3.6	А	
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	28		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	18		
Single Pulse Avalanche Energy		E <sub>AS</sub>	16.2	mJ	
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	D	4	W	
	T <sub>C</sub> = 125 °C	P <sub>D</sub>	1.3	vv	
Operating Junction and Storage Temperature F	Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount <sup>c</sup>	R <sub>thJA</sub>	110	°C/W	
Junction-to-Foot (Drain)		R <sub>thJF</sub>	34	0/10	

#### Notes

a. Package limited.

b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

c. When mounted on 1" square PCB (FR4 material).

## **STN4828**

Static         Static $V_{GS} = 0 V, I_p = 250 \mu A$ 60         -         - $V_{GS}$ Gate-Source Threshold Voltage $V_{GS}(h)$ $V_{DS} = V_{GS}, I_p = 250 \mu A$ 1.5         2.0         2.5 $V_{GS}$ Gate-Source Leakage $I_{GSS}$ $V_{DS} = 0 V, V_{GS} = \pm 20 V$ -         - $\pm 100$ nA           Zero Gate Voltage Drain Current $I_{DSS}$ $V_{GS} = 0 V$ $V_{DS} = 60 V, T_J = 125 °C$ -         -         1 $\mu A$ On-State Drain Current <sup>a</sup> $I_{D(an)}$ $V_{GS} = 0 V$ $V_{DS} = 60 V, T_J = 125 °C$ -         -         150           Drain-Source On-State Resistance <sup>a</sup> $I_{D(an)}$ $V_{GS} = 10 V$ $I_D = 4.5 A, T_J = 125 °C$ -         0.028         -         -         40           Drain-Source On-State Resistance <sup>a</sup> $V_{GS} = 10 V$ $I_D = 4.5 A, T_J = 125 °C$ -         0.081         -         -         40           Drain-Source On-State Resistance <sup>a</sup> $V_{GS} = 10 V$ $I_D = 4.5 A, T_J = 175 °C$ -         0.081         -         -         40         -         40         -         50         60         -         -	<b>SPECIFICATIONS</b> ( $T_c = 25 \text{ °C}$ , unless otherwise noted)							
$ \begin{array}{ c c c c } \hline Drain-Source Breakdown Voltage & V_{DS} & V_{GS} = 0 V, V_{GS} = 250 \ \mu A & 60 & - & - & \\ \hline Gate-Source Leakage & I_{GSS} & V_{DS} = 0 V, V_{GS} = 250 \ \mu A & 1.5 & 2.0 & 2.5 & \\ \hline Gate-Source Leakage & I_{GSS} & V_{DS} = 0 V, V_{GS} = 20 V & - & - & 4 \ 100 & nA & \\ \hline Product Particle Part Part Part Part Part Part Part Part$	PARAMETER	SYMBOL			MIN.	TYP.	MAX.	UNIT
$ \begin{array}{c c c c c c c } \hline Gate-Source Threshold Voltage $V_{GS(th)}$ & V_{DS} = V_{GS}, b = 250 \ \mu & 1.5 & 2.0 & 2.5 \\ \hline Gate-Source Leakage & l_{GSS} & V_{DS} = 0 \ V, V_{GS} = \pm 20 \ V & - & - & \pm 100 & nA \\ \hline Gate-Source Leakage & l_{GSS} & V_{DS} = 0 \ V, V_{GS} = 60 \ V & - & - & 1 & V_{GS} & V_{DS} & 0 \ V_{DS} = 60 \ V & - & - & 10 & V_{DS} & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & $	Static	-						
$ \begin{array}{c c c c c c c } \hline \mbox{Gate-Source Inveshold Voltage} & V_{GS(th)} & V_{DS} = V_{GS}, \mbox{I}_{D} = 250 \ \mu A & 1.5 & 2.0 & 2.5 & 1 & 1.5 & 1.5 & 2.0 & 2.5 & 1.5$	Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> =	$V_{GS} = 0 V, I_D = 250 \mu A$		-	-	V
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μΑ	1.5	2.0	2.5	V
$ \begin{array}{ c c c c c } \mbox{Zero Gate Voltage Drain Current} & I_{DSS} & V_{GS} = 0 V & V_{DS} = 60 V, T_J = 125 \ ^{\circ}{\rm C} & - & - & 50 \\ \hline V_{GS} = 0 V & V_{DS} = 60 V, T_J = 175 \ ^{\circ}{\rm C} & - & - & 150 \\ \hline V_{GS} = 0 V & V_{DS} = 50 V, T_J = 175 \ ^{\circ}{\rm C} & - & - & 150 \\ \hline V_{GS} = 10 V & V_{DS} \geq 5 V & 20 & - & - & A \\ \hline V_{GS} = 10 V & I_D = 4.5 \ A, T_J = 125 \ ^{\circ}{\rm C} & - & 0.066 & - \\ \hline V_{GS} = 10 V & I_D = 4.5 \ A, T_J = 125 \ ^{\circ}{\rm C} & - & 0.088 & - \\ \hline V_{GS} = 10 V & I_D = 4.5 \ A, T_J = 125 \ ^{\circ}{\rm C} & - & 0.088 & - \\ \hline V_{GS} = 10 V & I_D = 4.5 \ A, T_J = 175 \ ^{\circ}{\rm C} & - & 0.088 & - \\ \hline V_{GS} = 10 V & I_D = 4.5 \ A, T_J = 175 \ ^{\circ}{\rm C} & - & 0.081 & - \\ \hline V_{GS} = 4.5 V & I_D = 4 \ A & 0.030 & - \\ \hline V_{GS} = 4.5 V & I_D = 4 \ A & 0.030 & - \\ \hline V_{GS} = 4.5 V & I_D = 4 \ A & 0.030 & - \\ \hline V_{GS} = 15 \ V, I_D = 4.5 \ A & - & 15 & - & S \\ \hline Dynamic \ b & & & & & & & & \\ \hline Dynamic \ b & & & & & & & & & & \\ \hline Dut Capacitance & C_{ISS} & V_{GS} = 0 \ V \\ Output Capacitance & C_{ISS} & V_{GS} = 0 \ V_{GS} = 0 \ V \\ V_{DS} = 25 \ V, f = 1 \ MHz & - & 110 & 140 \\ P \ Reverse Transfer Capacitance & C_{rSS} & V_{GS} = 10 \ V \\ \hline Dut Capacitance \ Capacita$	Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	0 V, $V_{GS} = \pm 20 V$	-	-	± 100	nA
$ \begin{array}{ c c c c c } \hline V_{GS} = 0 & V_{DS} = 60 & V, \ T_J = 175 \ ^{\circ}{\rm C} & - & - & 150 \\ \hline V_{GS} = 10 & V_{DS} \geq 5 & 20 & - & - & A \\ \hline V_{GS} = 10 & V_{DS} \geq 5 & 20 & - & - & A \\ \hline V_{GS} = 10 & V_{DS} \geq 5 & 20 & - & - & 0.028 & - & \\ \hline V_{GS} = 10 & V_{DS} = 4.5 & A, \ T_J = 125 \ ^{\circ}{\rm C} & - & 0.066 & - & \\ \hline V_{GS} = 10 & V_{DS} = 4.5 & A, \ T_J = 125 \ ^{\circ}{\rm C} & - & 0.081 & - & \\ \hline V_{GS} = 10 & V_{DS} = 4.5 & V_{DS} = 15 \ ^{\circ}{\rm C} & - & 0.081 & - & \\ \hline V_{GS} = 10 & V_{DS} = 4.5 & V_{DS} = 15 \ ^{\circ}{\rm C} & - & 0.081 & - & \\ \hline V_{GS} = 4.5 & V_{DS} = 15 \ ^{\circ}{\rm C} & - & 0.030 & - & \\ \hline V_{GS} = 4.5 & V_{DS} = 15 \ ^{\circ}{\rm C} & - & 0.030 & - & \\ \hline V_{GS} = 4.5 & V_{DS} = 15 \ ^{\circ}{\rm C} & - & 0.030 & - & \\ \hline V_{DS} = 25 \ ^{\circ}{\rm C} & - & 15 & - & \\ \hline Dynamic ^{b} & & & & \\ \hline Dutput \ Capacitance & C_{Iss} & & & \\ \hline Dutput \ Capacitance & C_{rss} & & & \\ \hline Output \ Capacitance & C_{rss} & & \\ \hline Output \ Capacitance & C_{rss} & & \\ \hline Cutal \ Gate \ Charge \ ^{\circ} & Q_{g} & & \\ \hline Cutal \ Gate \ Charge \ ^{\circ} & Q_{g} & & \\ \hline Cate \ Charge \ ^{\circ} & Q_{g} & & \\ \hline Cate \ Charge \ ^{\circ} & Q_{g} & & \\ \hline Cate \ Charge \ ^{\circ} & Q_{g} & & \\ \hline Turn \ On \ Delay \ Time \ ^{\circ} & t_{d(off)} & \\ \hline Turn \ Of \ Delay \ Time \ ^{\circ} & t_{d(off)} & \\ \hline Turn \ Of \ Delay \ Time \ ^{\circ} & t_{d(off)} & \\ \hline Turn \ Of \ Delay \ Time \ ^{\circ} & t_{d(off)} & \\ \hline Turn \ Of \ Delay \ Time \ ^{\circ} & t_{d(off)} & \\ \hline Turn \ Of \ Delay \ Time \ ^{\circ} & t_{d(off)} & \\ \hline Turn \ Of \ Delay \ Time \ ^{\circ} & t_{d(off)} & \\ \hline Turn \ ^{\circ} \ Delay \ Time \ ^{\circ} \ t_{d(off)} & \\ \hline Turn \ ^{\circ} \ Delay \ Time \ ^{\circ} \ t_{d(off)} & \\ \hline Turn \ ^{\circ} \ Delay \ Time \ ^{\circ} \ Turn \ ^{\circ} \ Cate \ ^{\circ} \ Turn \ ^{\circ} \ Cate \ ^{\circ}$			$V_{GS} = 0 V$	V <sub>DS</sub> = 60 V	-	-	1	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	50	μA
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$				V <sub>DS</sub> = 60 V, T <sub>J</sub> = 175 °C	-	-	150	
$ \begin{array}{ c c c c c c } \hline \mbox{Drain-Source On-State Resistance $^a$} & $P_{OS(on)}$ & $V_{GS} = 10 $V$ & $I_D = 4.5 $A, $T_J = 125 $^{\circ}$C$ & $-$ & $0.066$ & $-$ \\ \hline V_{GS} = 10 $V$ & $I_D = 4.5 $A, $T_J = 175 $^{\circ}$C$ & $-$ & $0.081$ & $-$ \\ \hline V_{GS} = 10 $V$ & $I_D = 4.5 $A, $T_J = 175 $^{\circ}$C$ & $-$ & $0.081$ & $-$ \\ \hline V_{GS} = 10 $V$ & $I_D = 4.5 $A$ & $T_J = 175 $^{\circ}$C$ & $-$ & $0.081$ & $-$ \\ \hline V_{GS} = 10 $V$ & $I_D = 4.5 $A$ & $T_J = 175 $^{\circ}$C$ & $-$ & $0.081$ & $-$ \\ \hline V_{GS} = 10 $V$ & $I_D = 4.5 $A$ & $-$ & $15$ & $-$ & $S$ \\ \hline \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \$	On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>		$V_{DS} \ge 5 V$	20	-	-	A
$ \begin{array}{ c c c c c c c c c } \hline Page & Pa$				5			-	
$ \begin{array}{ c c c c c c c } \hline V_{GS} = 4.5 \ V &  l_D = 4 \ Alpha & 0.030 & - \\ \hline Forward Transconductance ^f & g_{fs} & V_{DS} = 15 \ V, \ l_D = 4.5 \ A & - & 15 & - & S \\ \hline Dynamic ^b & & & & & & & & & & & & & & & & & & $	Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>					-	Ω
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $		()			-			
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $				5				
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$		9 <sub>fs</sub>	V <sub>DS</sub>	= 15 V, I <sub>D</sub> = 4.5 A	-	15	-	S
$ \begin{array}{ c c c c c c c } \hline Output Capacitance & C_{oss} & V_{GS} = 0 \ V & V_{DS} = 25 \ V, \ f = 1 \ MHz & - & 110 & 140 & PF & 101 & 101 & 140 & PF & 101 & 101 & 100 $	-	Г			[	T	[	T
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Input Capacitance	C <sub>iss</sub>	_	V <sub>GS</sub> = 0 V V <sub>DS</sub> = 25 V, f = 1 MHz	-	600	750	pF
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$		-	110	140	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Reverse Transfer Capacitance	C <sub>rss</sub>			-	50	62	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Total Gate Charge <sup>c</sup>	Qg			-	11.7	18	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{GS} = 10 \text{ V}$	$V_{DS} = 30 \text{ V}, \text{ I}_{D} = 5.3 \text{ A}$	-	1.8	2.7	nC
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>	]		-	2.8	4.2	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Gate Resistance	Rg		f = 1 MHz		-	6	Ω
Turn-Off Delay Time ° $t_{d(off)}$ $I_D = 30.0$ , $H_L = 0.0.22$ $ 22.4$ $33.5$ Fall Time ° $t_f$ $ 2.1$ $3.2$ Source-Drain Diode Ratings and Characteristics <sup>b</sup>	Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>		V <sub>DD</sub> = 30 V. Βι = 6.8 Ω		7	11	
Turn-Off Delay Time ° $t_{d(off)}$ $I_D \cong 4.4 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$ -22.433.5Fall Time ° $t_f$ -2.13.2Source-Drain Diode Ratings and Characteristics <sup>b</sup>	Rise Time <sup>c</sup>	t <sub>r</sub>	V <sub>DD</sub> =			3.3	5	- ns
Source-Drain Diode Ratings and Characteristics <sup>b</sup>	Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	22.4	33.5	
	Fall Time <sup>c</sup>	t <sub>f</sub>			-	2.1	3.2	
Pulsed Current <sup>a</sup> I <sub>SM</sub> 28 A	Source-Drain Diode Ratings and Characteristics <sup>b</sup>							
	Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	28	Α
Forward Voltage         V <sub>SD</sub> I <sub>F</sub> = 2 A, V <sub>GS</sub> = 0 V         -         0.75         1.1         V	Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> =	$I_{F} = 2 A, V_{GS} = 0 V$		0.75	1.1	V

Notes

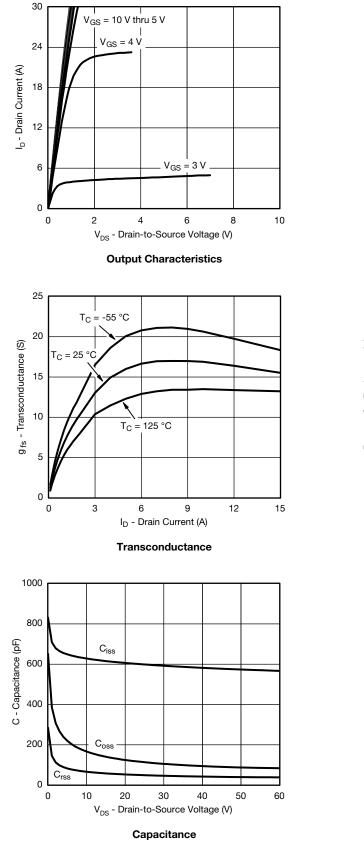
a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
b. Guaranteed by design, not subject to production testing.
c. Independent of operating temperature.

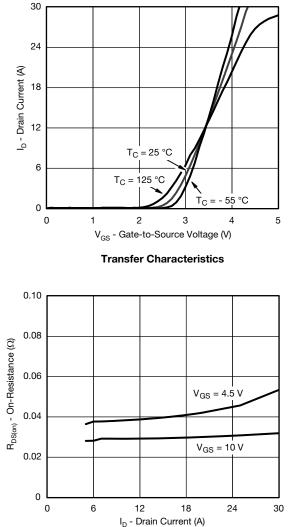
Bsemi

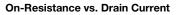
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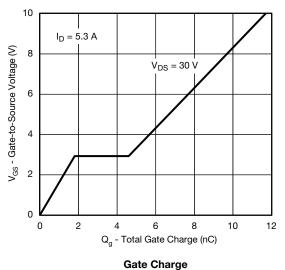


## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

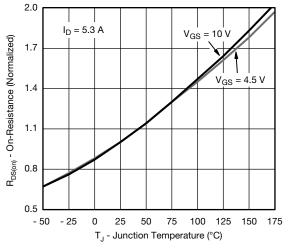




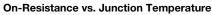


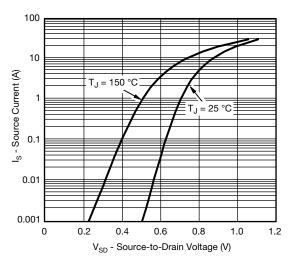




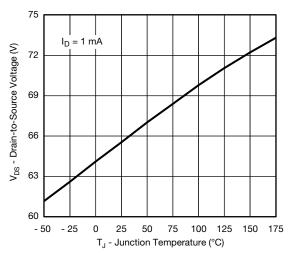


### **TYPICAL CHARACTERISTICS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)

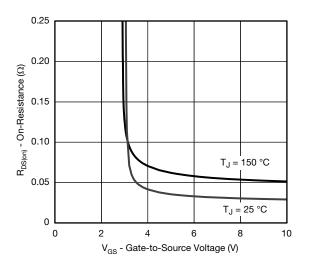




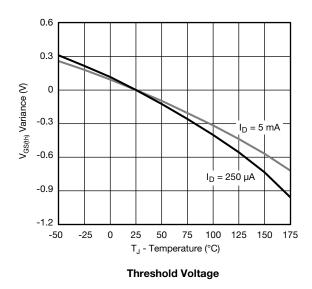
Source Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature



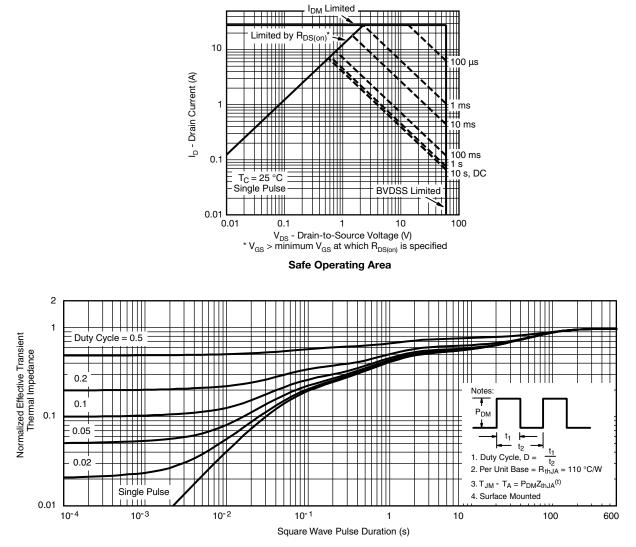
On-Resistance vs. Gate-to-Source Voltage



服务热线:400-655-8788

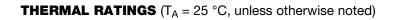


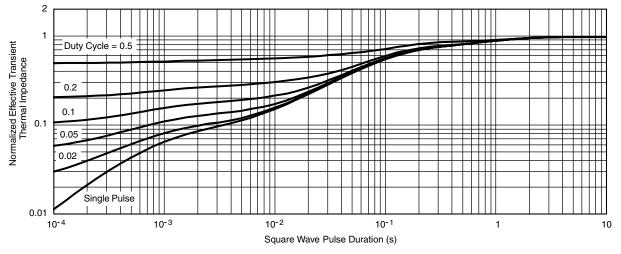
#### **THERMAL RATINGS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



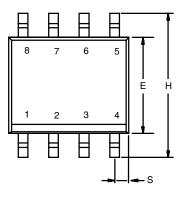


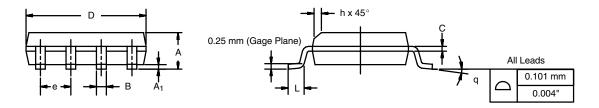


Normalized Thermal Transient Impedance, Junction-to-Foot



# SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012

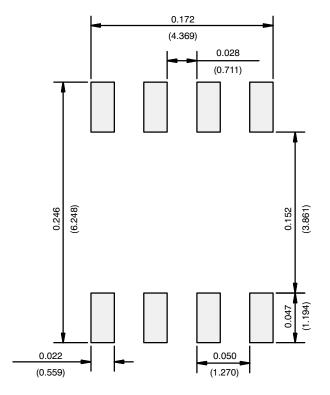




	MILLIM	IETERS	INCHES		
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A <sub>1</sub>	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					



### **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)



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